

RoHS

COMPLIANT HALOGEN

FREE

Vishay Siliconix

P-Channel 30 V (D-S) MOSFET

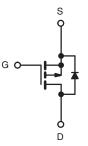
PRODUCT SUMMARY						
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A) ^d	Q _g (Typ.)			
- 30	0.0205 at V _{GS} = - 10 V	- 11.6	12.4 nC			
	0.0375 at V_{GS} = - 4.5 V	- 8.6	12.4110			

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % Rg Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

· Load Switches, Adaptor Switch - Notebook PCs



P-Channel MOSFET

SO-8 S 8 1 D S D 2 7 S 6 D 3 G D 5 4 Top View

Ordering Information: Si4487DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	- 30	V		
Gate-Source Voltage		V _{GS}	± 25	v	
	T _C = 25 °C		- 11.6		
Continuous Drain Current (T ₁ = 150 °C)	T _C = 70 °C		- 9.3		
Continuous Drain Current (1) = 150°C)	T _A = 25 °C	I _D	- 8.2 ^{a, b}		
	T _A = 70 °C		- 6.5 ^{a, b}	٨	
Pulsed Drain Current	I _{DM}	- 50	— A		
Continuous Courses Dusin Diada Current	T _C = 25 °C	1	- 4.1		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 2.0 ^{a, b}		
Avalanche Current		I _{AS}	- 15		
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	11.25	mJ	
	T _C = 25 °C		5.0		
Marian Distribution	T _C = 70 °C		3.2	14/	
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	W	
	T _A = 70 °C	1 -	1.6 ^{a, b}		
Operating Junction and Storage Temperature Rang	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	39	50	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	C/W	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

c. Maximum under steady state conditions is 85 °C/W. d. Based on $T_C = 25$ °C.

b. t = 10 s.

Si4487DY

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L 050 vA		- 25		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		4.7			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.2		- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 25 V$			± 100	nA	
Zana Cata Maltana Duain Cumunat	1	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			- 5	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	- 30			Α	
	_	V _{GS} = - 10 V, I _D = - 10 A		0.0165	0.0205	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 7 A		0.030	0.0375		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 10 A		20		S	
Dynamic ^b	•			•			
Input Capacitance	C _{iss}			1075		pF	
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		215			
Reverse Transfer Capacitance	C _{rss}			180			
Total Gate Charge	Qg	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -10 \text{ A}$		24	36		
				12.4	18.6	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -10 \text{ A}$		3.4			
Gate-Drain Charge	Q _{gd}			5.8			
Gate Resistance	R _g	f = 1 MHz	1.1	5.5	11	Ω	
Turn-On Delay Time	t _{d(on)}			9	18		
Rise Time	t _r	V_{DD} = - 15 V, R_L = 1.5 Ω		8	16	1	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		28	50		
Fall Time	t _f			10	20		
Turn-On Delay Time	t _{d(on)}			42	75	ns	
Rise Time	t _r	V_{DD} = - 15 V, R_L = 1.5 Ω		31	60	-	
Turn-Off DelayTime	t _{d(off)}	$\text{I}_\text{D}\cong$ - 10 A, V_GEN = - 4.5 V, R_g = 1 Ω		21	40		
Fall Time	t _f			15	30		
Drain-Source Body Diode Characterist	ics			•			
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 4.1	٨	
Pulse Diode Forward Current	I _{SM}				- 50	A	
Body Diode Voltage	V _{SD}	I _S = - 2 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			23	45	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	$L = E \Lambda dl/dt = 100 \Lambda/tra T = 05 00$		12	23	nC	
Reverse Recovery Fall Time	t _a	I _F = - 5 A, dl/dt = 100 A/μs, T _J = 25 °C		9		ns	
Reverse Recovery Rise Time	t _b			15			

Notes:

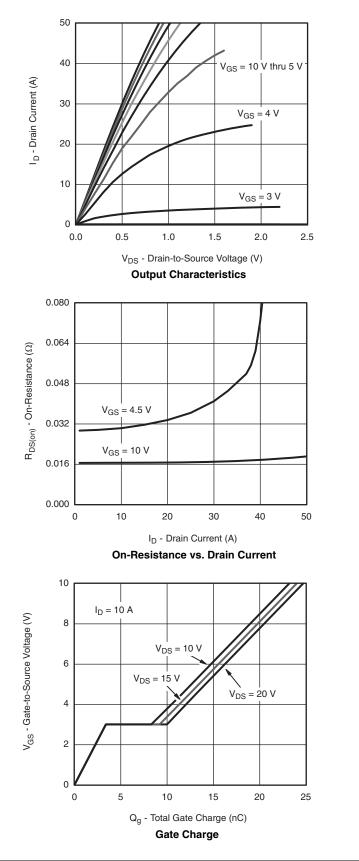
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

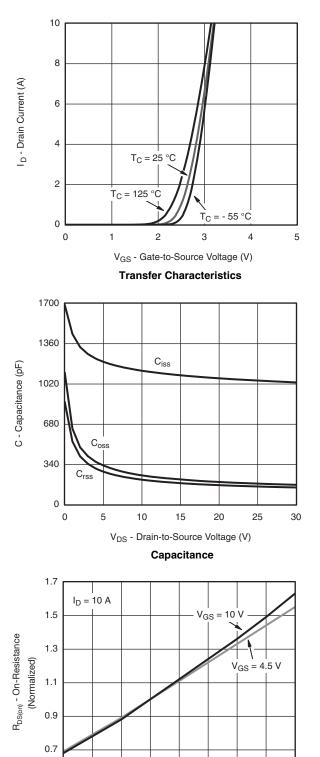
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





0.5

- 50

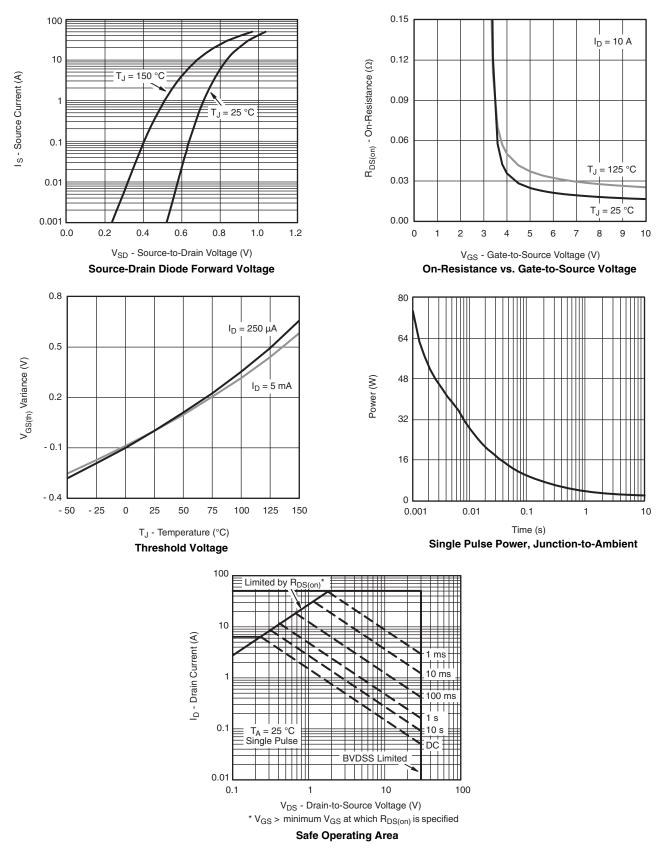
- 25

0

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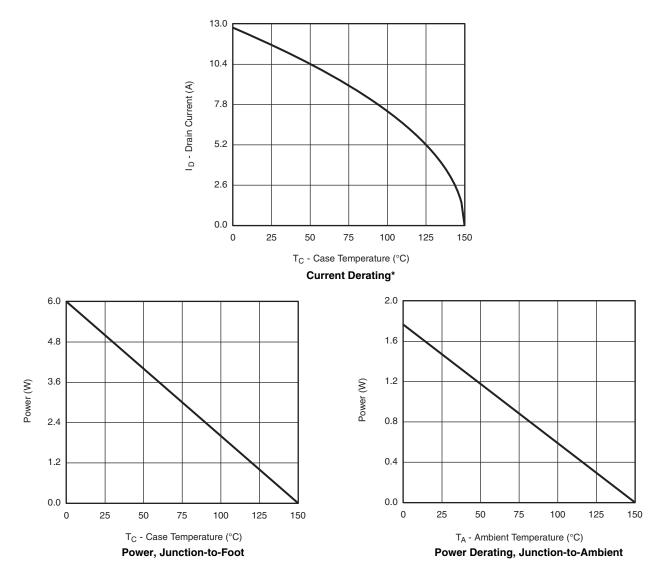
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Si4487DY Vishay Siliconix

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

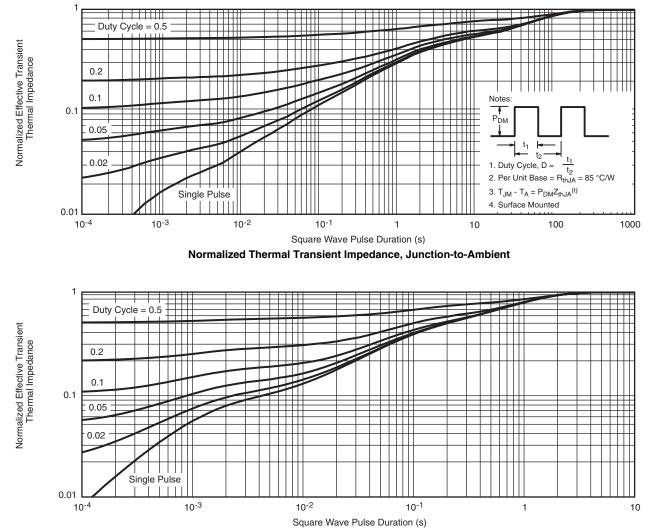


* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?65473.



Package Information

Vishay Siliconix

SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





	MILLIM	IETERS	INCHES			
DIM	Min	Мах	Min	Max		
A	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050 BSC			
н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498						

Application Note 826

Vishay Siliconix



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index



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Revision: 01-Jan-2025

1